

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A manufacturing method of a display device in a plasma treatment chamber comprising the step of:

forming a wiring by partially etching a conductor film over a substrate by discharging a reactive gas plasma to the plasma treatment chamber from a plasma treatment means having one set of electrodes contained therein for generating the plasma at a pressure of 5 to 800 Torr from a reactive gas introduced to the plasma treatment means,

wherein the plasma treatment means is provided in the plasma treatment chamber.

2. (Currently Amended) A manufacturing method of a display device in a plasma treatment chamber comprising the step of:

forming a wiring by partially etching a conductor film over a substrate by discharging a reactive gas plasma to the plasma treatment chamber from a plasma treatment means having a plurality of sets of electrodes contained therein for generating the plasma at a pressure of 5 to 800 Torr from a reactive gas introduced to the plasma treatment means,

wherein the plasma treatment means is provided in the plasma treatment chamber.

3. (Canceled)

4. (Currently Amended) A manufacturing method of a display device comprising the steps of:

forming a conductor film over a substrate;

forming a resist mask over the conductor film; and

partially etching the conductor film at a pressure of 5 to 800 Torr by discharging a reactive gas plasma to a plasma treatment chamber from a plasma treatment means having at least one set of electrodes contained therein for generating the plasma from a reactive gas introduced to the plasma treatment means, over with the resist mask-as a mask-and thereby

forming a wiring,_s

wherein the plasma treatment means is provided in the plasma treatment chamber.

5. (Currently Amended) A manufacturing method of a display device comprising the steps of:

forming a conductor film over a substrate;

forming a resist mask over the conductor film; and

partially etching the conductor film at a pressure of 5 to 800 Torr by discharging a ~~reactive gas plasma to a plasma treatment chamber from a plasma treatment means having a plurality of sets of electrodes contained therein for generating the plasma from a reactive gas introduced to the plasma treatment means, over with the resist mask as a mask and thereby~~ forming a wiring,_s

wherein the plasma treatment means is provided in the plasma treatment chamber.

6. (Previously Presented) The manufacturing method of the display device according to any of claims 1, 2, 4 and 5, wherein the substrate has a size of 1,000 x 1,200 mm² or more.

7. (Previously Presented) The manufacturing method of the display device according to any of claims 1, 2, 4 and 5, wherein the plasma treatment means scans the substrate in one direction.

8. (Previously Presented) The manufacturing method of the display device according to any of claims 1, 2, 4 and 5, wherein the plasma treatment means alternately scans the substrate in a row direction and in a column direction.

9. (Previously Presented) The manufacturing method of the display device according to any of claims 4 and 5, wherein the resist mask is formed by use of liquid droplet jetting means.

10-11. (Canceled)

12. (New) The manufacturing method of the display device according to any of claims 1, 2, 4 and 5, further comprising:
moving the plasma treatment means along a rail.